



| nems |  | TMG(E)-5 $\square \square$, TJG(E)-5 $\square \square \mathrm{V}$ SPECIFICATION |  |  | $\begin{gathered} \hline \text { FILE No. } \\ \text { REV. } \\ \text { Page } \\ \hline \end{gathered}$ | $\begin{array}{ll} \hline: & E- \\ : & \\ : & 2 \\ \hline \end{array}$ | $\begin{array}{cc} \text { E-V-AT05 } \\ \text { C } \\ 1 \quad 4 \\ \hline \end{array}$ |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
|  | 7 | Operating Force | Applied in the direction of operation | OF | [ $\begin{aligned} & 100 \pm 50 \mathrm{~g} \\ & {[0.98 \pm .49 \mathrm{~N}]}\end{aligned}$ | $\left[\begin{array}{c}160 \pm 50 \mathrm{~g} \\ {[1.568 \pm .49 \mathrm{~N}]}\end{array}\right.$ | [ $\begin{aligned} & 260 \pm 50 \mathrm{~g} \\ & {[2.548 \pm .4 \mathrm{~N}]}\end{aligned}$ |
|  | 8 | Stroke | Placing the switch such that the direction of switch operation is vertical and then gradually increasing the load applied to the stem, the stroke distance for the stem to come to a stop shall be measured | 0.25+0.1/-0.2mm |  |  |  |
|  | 9 | Stop Strength | Placing the switch such that the direction of switch operation is vertical, a static load of $3 \mathrm{kgf}(29.4 \mathrm{~N})$ shall be applied in the direction of stem operation for a period of 15 seconds | 1)As shown in item 4~7 <br> 2)Contact Resistance: 200m $\Omega$ Max <br> 3)Insulation Resistance: 10MS min |  |  |  |
|  | 10 | Solder Heat Resistance | 1.PCB is 1.6 mm in thickness 2.SMT Type ~TMG(E), TJG(E)-5 Series(4/4) | 1)As shown in item 4 , 5 <br> 2)Contact Resistance: 200m $\Omega$ Max <br> 3)Insulation Resistance: $10 \mathrm{M} \Omega \mathrm{min}$ |  |  |  |
|  | 11 | Vibration | Shall be vibrated in accordance with Method 201A of <br> MIL-STD-202F <br> 1.Swing distance: 1.5 mm <br> 2. Frequency: $10-55-10 \mathrm{~Hz}$ in 1-min/cycle. <br> 3.Direction: 3 vertical directions including the directions of operation <br> 4.Test time: 2 hours each direction | $\begin{array}{r} \text { 1)As } \\ \text { 2)Cc } \\ 20 \\ 3) \mathrm{Ins} \\ 10 \mathrm{M} \end{array}$ | As shown <br> Contact Re $200 \mathrm{~m} \Omega \mathrm{M}$ <br> nsulation $\mathrm{M} \Omega \mathrm{min}$ | in item 4~ <br> esistance <br> ax <br> Resistance |  |
|  | 12 | Shock | Shall be shocked in accordance with Method 213B condition A of MIL-STD-202F <br> 1.Acceleration; 50G <br> 2.Action time: $11 \pm 1 \mathrm{~m}$ seconds <br> 3. Testing Direction: 6 sides <br> 4. Test Cycle: 3 times in each direction |  |  | Ditto |  |


|  |  | TMG(E)-5 $\square \square$, TJG(E)-5 $\square \square \mathrm{V}$ SPECIFICATION |  |  | $\mathrm{E}-\mathrm{V}$ <br> 3 |  |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
|  | 13 Operating Life $\left.\begin{array}{l}\text { Measurements shall be made } \\ \text { following the test forth below: } \\ \text { 1.5 mA, 5 VDC resistive load } \\ \text { 2.Applying a static load the } \\ \text { operating force to the center of } \\ \text { the stem in the direction of } \\ \text { operation } \\ \text { Static Load = OF max } \\ \text { 3.Cycle of Operation: } \\ 1,000,000 \text { cycles min. } \\ \text { For } 100, ~ 160 \mathrm{gf}\end{array}\right\}$200,000 cycles min. <br> For 260 gf |  |  | 1.As shown <br> 2.Operating initial forc <br> 3.Contact R 10 1 Max <br> 4.Insulation 10M $\Omega$ min 5.Bounce: 10 m seco | m 4 $\pm 50$ ance: ance: <br> ax |  |
|  | 14 | Resistance Low Temperature | Following the test set forth below the sample shall be left in normal temperature and humidity conditions for 1 hour before the measurements are made: <br> 1.Temperature:- $25 \pm 3^{\circ} \mathrm{C}$ <br> 2.Time: 96 hours | 1)As shown <br> 2)Contact R 200m $\Omega$ Max <br> 3)Insulation $10 \mathrm{M} \Omega \mathrm{min}$ | $7 \sim 7$ <br> ce: <br> ance: |  |
|  | 15 | Resistance <br> High Temperature | Following the test set forth below the sample shall be left in normal temperature and humidity conditions for 1 hour before the measurements are made: <br> 1.Temperature: $80 \pm 2^{\circ} \mathrm{C}$ <br> 2.Time: 96 hours | Ditto |  |  |
|  | 16 | Humidity Resistance | Following the test set forth below the sample shall be left in normal temperature and humidity conditions for 1 hour before the measurements are made: <br> 1)Temperature: $40 \pm 2^{\circ} \mathrm{C}$ <br> 2)Relative Humidity: 90~95\% <br> 3) Time: 96 hours | Ditto |  |  |



## 5. SOLDERING CONDITIONS:

- Condition for Soldering TMG(E), TJG(E)-5 Series

- The condition mentioned above is the temperature on the Cu foil of the PCB surface. There are cases where board's temperature greatly differs from switch's surface be used not to allow switch's surface temperature to exceed $260^{\circ} \mathrm{C}$.
- Manual Soldering

| Soldering Temperature | Max. $350^{\circ} \mathrm{C}$ |
| :--- | :---: |
| Continuous Soldering Time | Max. 5 seconds |

- Precautions in Handling
1.Care should be exercised so that flux from the upper part of the printed circuit board does not adhere to the switch.
2.Except for washable type do not wash the switch body.
3.Press direction \& illustrated drawing:


